

MCT9001

Dual Phototransistor Optocouplers

Features

- Two isolated channels per package
- Two packages fit into a 16 lead DIP socket
- Underwriters Laboratory (U.L.) recognized File E90700
- VDE approved for IEC60747-5-2

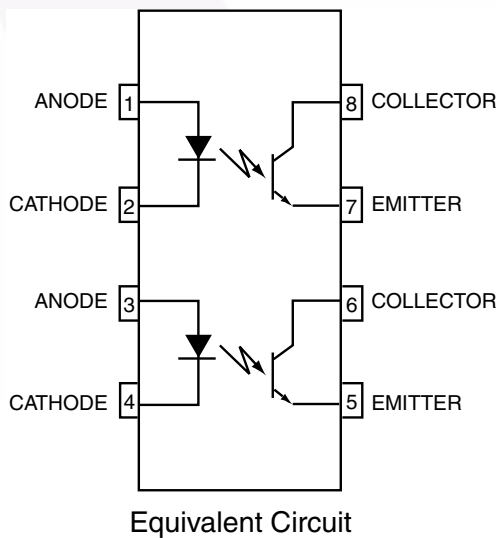
Applications

- AC line/digital logic – isolate high voltage transients
- Digital logic/digital logic – eliminate spurious grounds
- Digital logic/AC triac control – isolate high voltage transients
- Twisted pair line receiver – eliminate ground loop feedthrough
- Telephone/telegraph line receiver – isolate high voltage transients
- High frequency power supply feedback control – maintain floating grounds and transients
- Relay contact monitor – isolate floating grounds and transients
- Power supply monitor – isolate transients

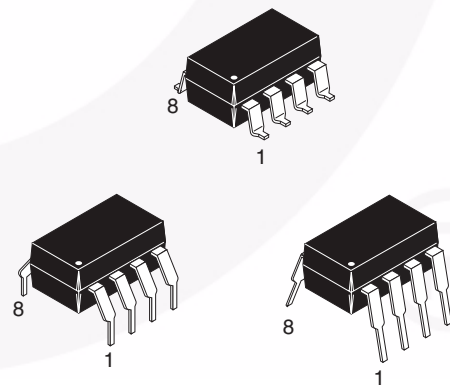
Description

The MCT9001 Optocoupler has two channels for density applications. For four channel applications, two-packages fit into a standard 16-pin DIP socket. Each channel is an NPN silicon planar phototransistor optically coupled to a gallium arsenide infrared emitting diode.

Schematic



Package Outlines



Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Rating	Value	Unit
TOTAL DEVICE			
T_{STG}	Storage Temperature	-55 to +150	°C
T_{OPR}	Operating Temperature	-55 to +100	°C
T_{SOL}	Lead Solder Temperature (Refer to Reflow Temperature Profile)	260 for 10 sec	°C
P_D	Total Device Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	400	mW
		4.83	mW/°C
EMITTER (Each channel)			
I_F	Forward Current – Continuous	60	mA
$I_F(pk)$	Forward Current – Peak (PW = 1 μ s, 300pps)	3	A
V_R	Reverse Voltage	5.0	V
P_D	LED Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C (Total Input)	100	mW
		1.1	mW/°C
DETECTOR (Each channel)			
I_C	Collector Current – Continuous	30	mA
P_D	Detector Power Dissipation @ $T_A = 25^\circ\text{C}$ Derate above 25°C	150	mW
		1.67	mW/°C

Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise specified)**Individual Component Characteristics**

Symbol	Parameter	Test Conditions	Min.	Typ.*	Max.	Unit
EMITTER						
V_F	Input Forward Voltage	$I_F = 10\text{mA}$		1.0	1.3	V
I_R	Reverse Current	$V_R = 5\text{V}$			10	μA
C_J	Junction Capacitance	$V_F = 0\text{V}, f = 1\text{MHz}$		50		pF
DETECTOR						
BV_{CEO}	Collector-Emitter Breakdown Voltage	$I_C = 0.5\text{mA}, I_F = 0$	55			V
BV_{ECO}	Emitter-Collector Breakdown Voltage	$I_E = 100\mu\text{A}, I_F = 0$	7			V
I_{CEO}	Collector-Emitter Dark Current	$V_{CE} = 24\text{V}, I_F = 0$		5	100	nA
		$V_{CE} = 24\text{V}, T_A = 85^\circ\text{C}$			50	μA
C_{CE}	Capacitance	$V_{CE} = 0\text{V}, f = 1\text{MHz}$		8		pF

Transfer Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.*	Max.	Units
SWITCHING TIMES (AC)						
Non-Saturated						
t_{on}	Turn-on Time	$R_L = 100\Omega, I_C = 2\text{mA}, V_{CC} = 10\text{V}$		3		μs
t_{off}	Turn-off Time			3		μs
t_r	Rise Time			2.4		μs
t_f	Fall Time			2.4		μs
Saturated						
t_{on}	Turn-on Time	$I_F = 16\text{mA}, R_L = 1.9\text{k}\Omega, V_{CE} = 5\text{V}$		2.4		μs
t_{off}	Turn-off Time			25.0		μs
DC CHARACTERISTICS						
CTR	Current Transfer Ratio, Collector-Emitter	$I_F = 5\text{mA}, V_{CE} = 5\text{V}$	50		600	%
$CTR_{(sat)}$		$I_F = 8\text{mA}, V_{CE} = 0.4\text{V}$	30			%
$V_{CE(sat)}$	Saturation Voltage	$I_F = 8\text{mA}, I_C = 2.4\text{mA}$			0.40	V

Isolation Characteristics

Symbol	Characteristic	Test Conditions	Min.	Typ.*	Max.	Units
V_{ISO}	Input-Output Isolation Voltage	$I_{I-O} \leq 10\mu\text{A}, t = 1\text{min.}$	5000			Vac(rms)
R_{ISO}	Isolation Resistance	$V_{I-O} = 500\text{VDC}$	10^{11}			Ω
C_{ISO}	Isolation Capacitance	$f = 1\text{MHz}$		0.5		pF

*All typicals at $T_A = 25^\circ\text{C}$

Typical Performance Curves

Fig. 1 Normalized CTR vs. Forward Current

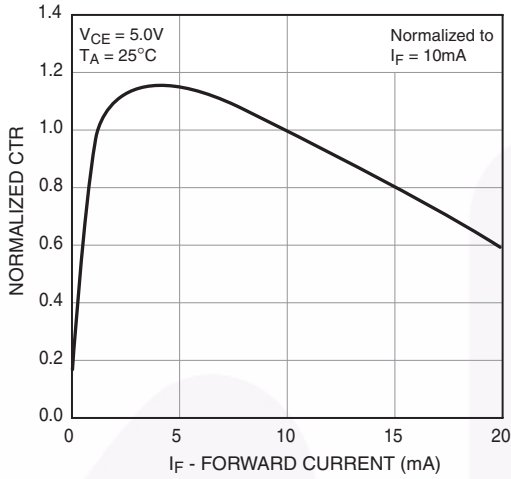


Fig. 2 Normalized CTR vs. Ambient Temperature

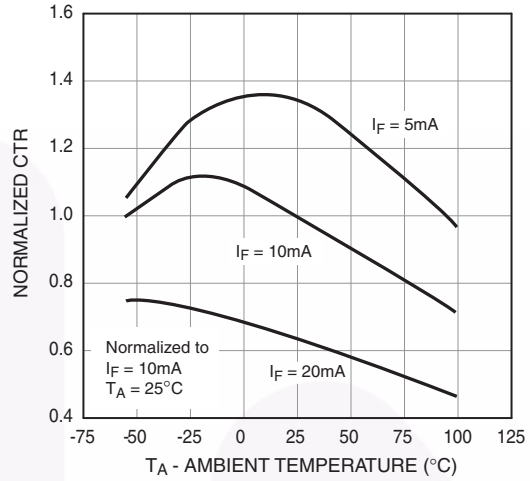


Fig. 3 Dark Current vs. Ambient Temperature

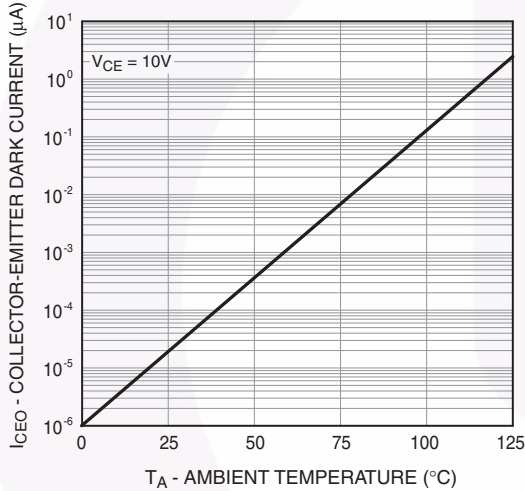


Fig. 4 Switching Speed vs. Load Resistor

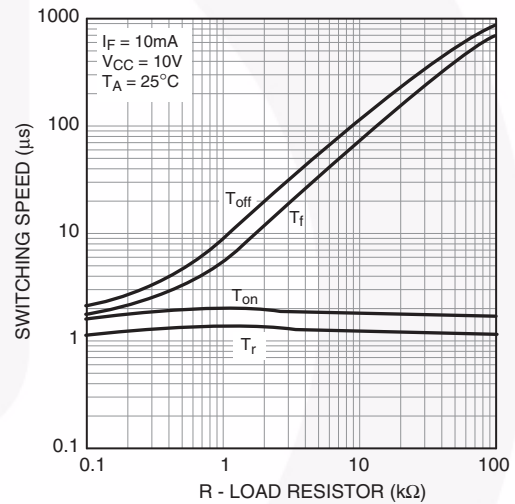


Fig. 5 LED Forward Voltage vs. Forward Current

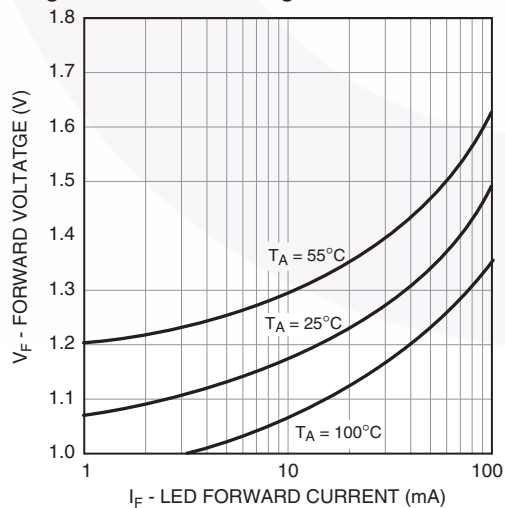
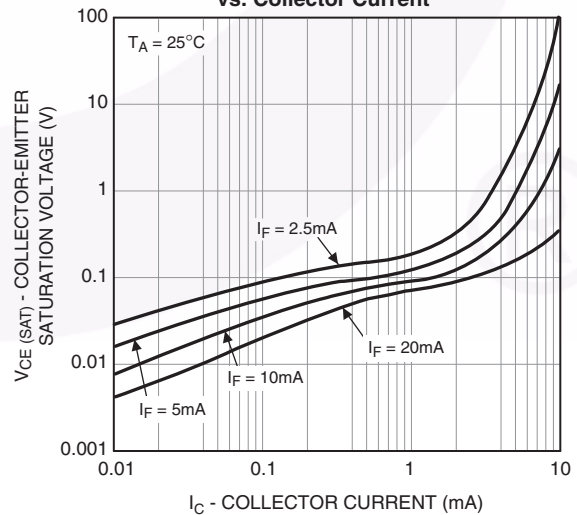
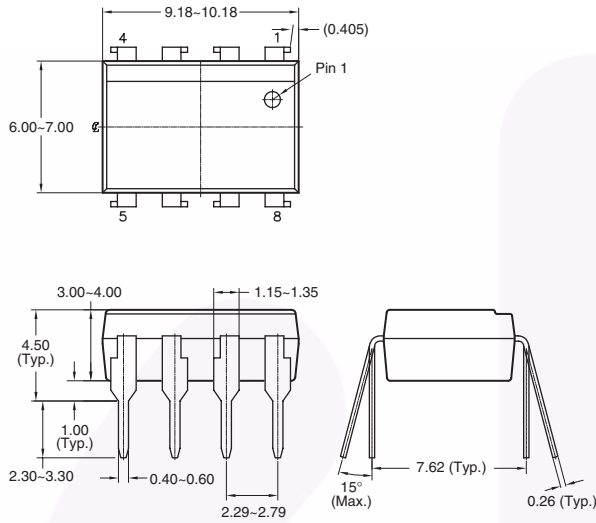


Fig. 6 Collector-Emitter Saturation Voltage vs. Collector Current

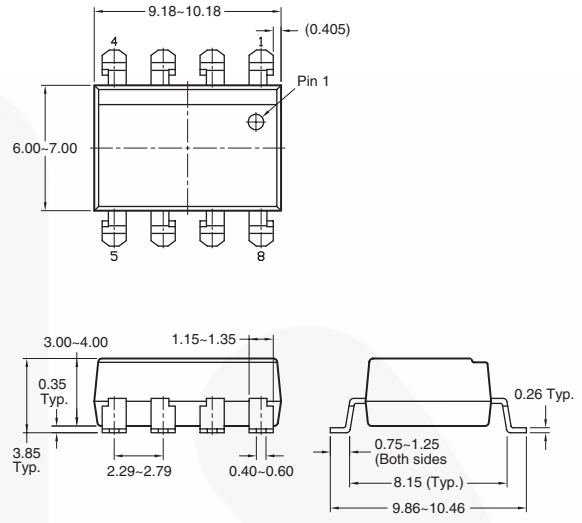


Package Dimensions

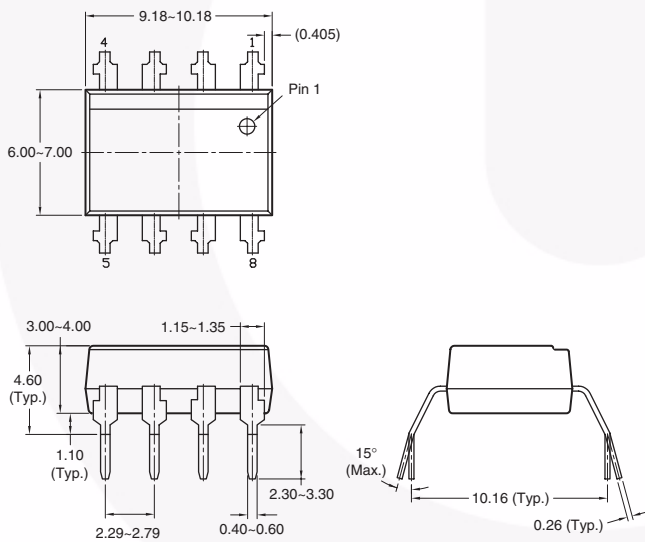
Through Hole



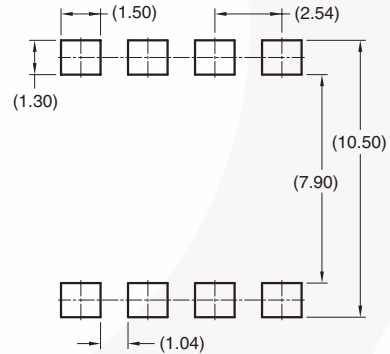
Surface Mount



0.4" Lead Spacing



Recommend Pad Layout for Surface Mount Leadform



Note:

All dimensions are in millimeters.

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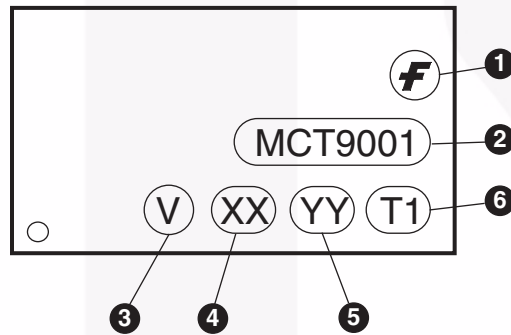
Always visit Fairchild Semiconductor's online packaging area for the most recent package drawings:

<http://www.fairchildsemi.com/packaging/>

Ordering Information

Option	Example Part Number	Description
No Option	MTC9001	Standard Through Hole
S	MTC9001S	Surface Mount Lead Bend
SD	MTC9001SD	Surface Mount; Tape and Reel
300	MTC9001300	VDE Approved
3S	MTC90013S	Surface Mount Lead Bend; VDE Approved
3SD	MTC90013SD	Surface Mount; Tape and Reel; VDE Approved
300W	MTC9001300W	0.4" Lead Spacing; VDE Approved

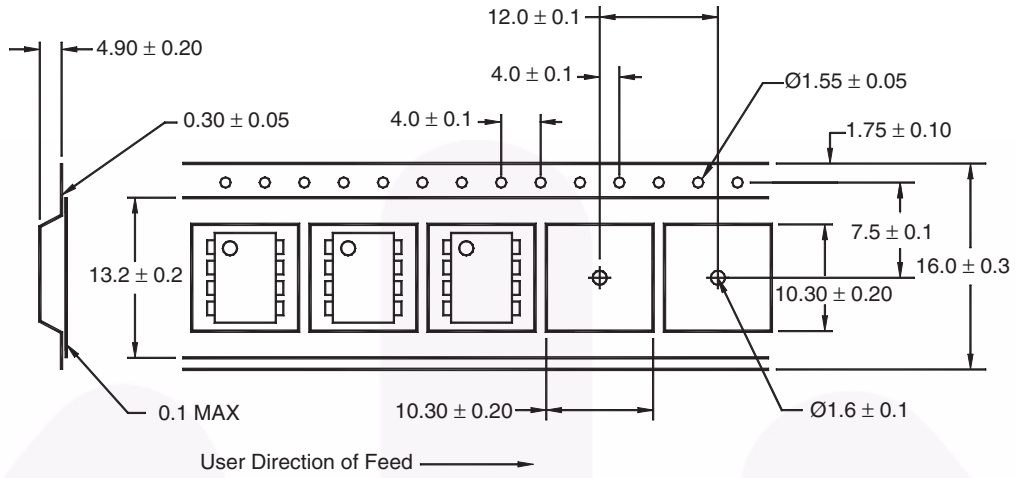
Marking Information



Definitions

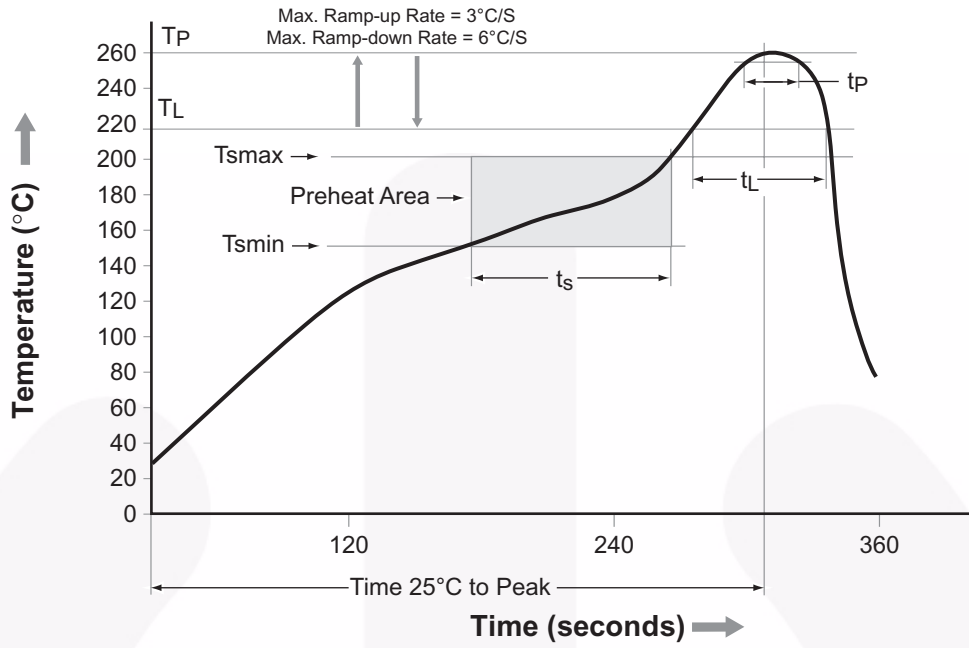
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	Two digit year code, e.g., '03'
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

Carrier Tape Specifications



Note:
All dimensions are in inches (millimeters)

Reflow Profile








Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmín)	150°C
Temperature Max. (Tsmáx)	200°C
Time (ts) from (Tsmín to Tsmáx)	60–120 seconds
Ramp-up Rate (tL to tp)	3°C/second max.
Liquidous Temperature (TL)	217°C
Time (tL) Maintained Above (TL)	60–150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (tp) within 5°C of 260°C	30 seconds
Ramp-down Rate (TP to TL)	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.



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Datasheet Identification	Product Status	Definition
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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